

ABSTRACT OF THE DISCLOSURE

ELECTROLESS DEPOSITION OF CONTINUOUS PLATINUM LAYER

5 A method for providing an electroless plating of a platinum containing layer is provided. A Ti^{3+} stabilization solution is provided. A Pt^{4+} stabilization solution is provided. A flow from the Ti^{3+} stabilization solution is combined with a flow from the Pt^{4+} stabilization solution and water to provide a diluted mixture of the Ti^{3+} stabilization solution and the Pt^{4+} stabilization solution. A substrate is exposed to the diluted mixture
10 of the Ti^{3+} stabilization solution and the Pt^{4+} stabilization solution.

Fig. 1